

东莞市东电科技有限公司产 品规格书

SPECIFICATION

DESCRIPTION **Chip Antenna**

PART NO. **DD160808-CD-01-R**

VERSION **V1.0**

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1.Naming Rules

Type: DD-ABCDEF-GH-IJ-K

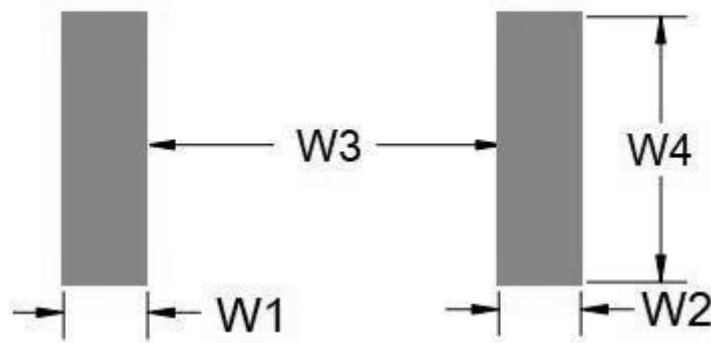
1. DD: Shortcut for Thinkte
2. ABCDEF: AB: Length(mm) CD: Width(mm)
For example: 160808 1.6mm*0.8mm
3. G: Material (C- Ceramic P-Polymer)
4. H: Feeding (S- Single D - Dual)
5. I J: Version (01 - 99)
6. K: Package (R - Reel, T - Tape)

2. Antenna Specification

Outline Dimensions	1.6x0.8x0.8(mm)
Ground Plane	1.6x0.8(mm)
Frequency Range	2.4GHz ~ 2.5GHz
Impedance	50 Ohm Nominal
Bandwidth (under -10dB return loss)	90MHz
Radiation	Omni-directional
Peak Gain	2.42dBi
Efficiency	75.51%
Polarization	Linear Polarization
Storage Temp	-40°C ~ +85°C
Color	Brown

3. Antenna Dimension

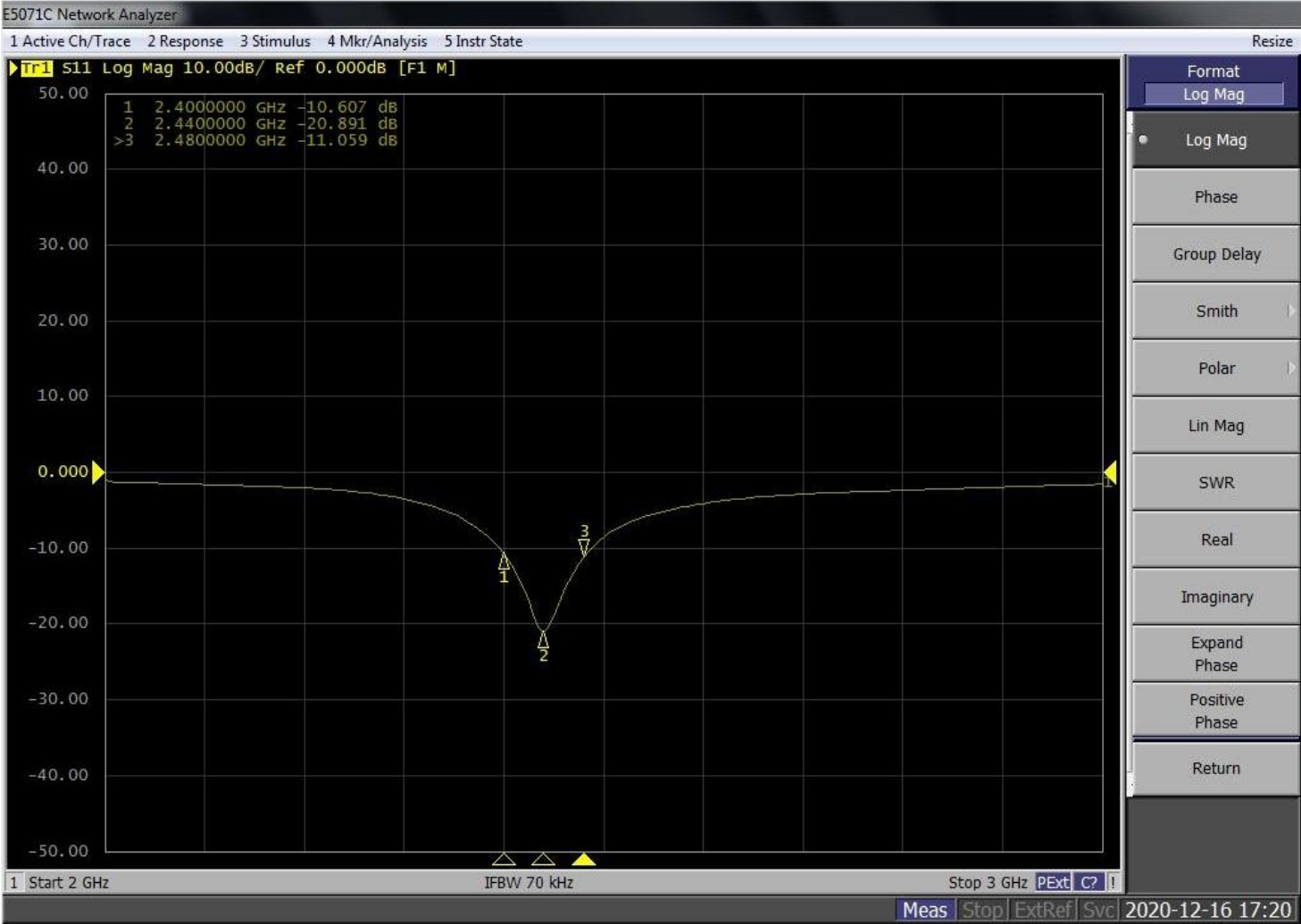
FootPrint (Unit : mm)



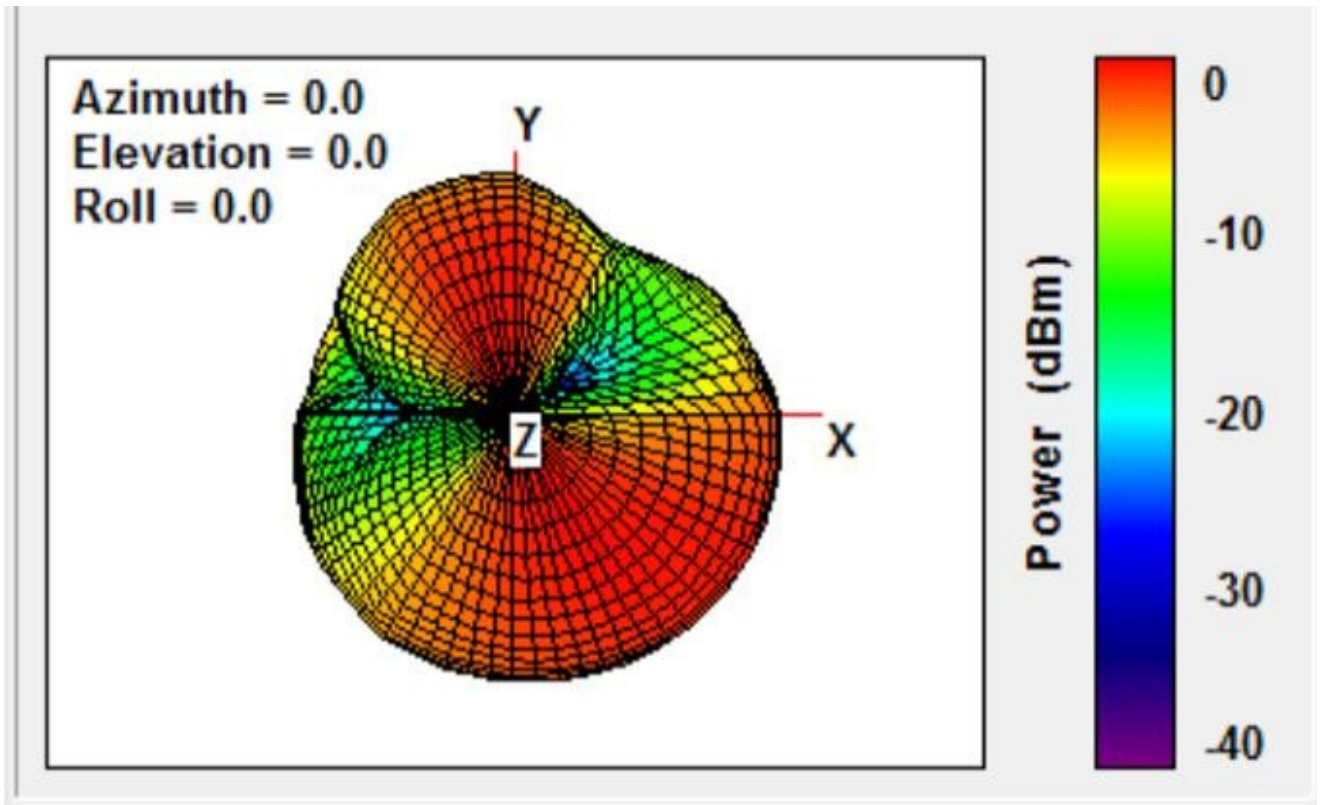
Type	W1	W2	W3	W4
DD1608	0.4 ± 0.2	0.4 ± 0.2	1.0 ± 0.2	1.0 ± 0.2

4. Test Data:

4.1 ELECTRICAL CHARACTERISTICSS11

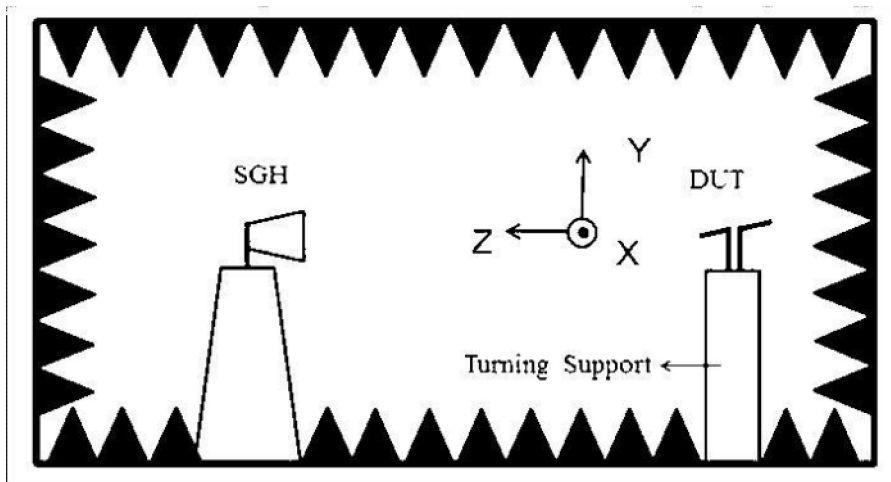


4.2 Radiation Pattern



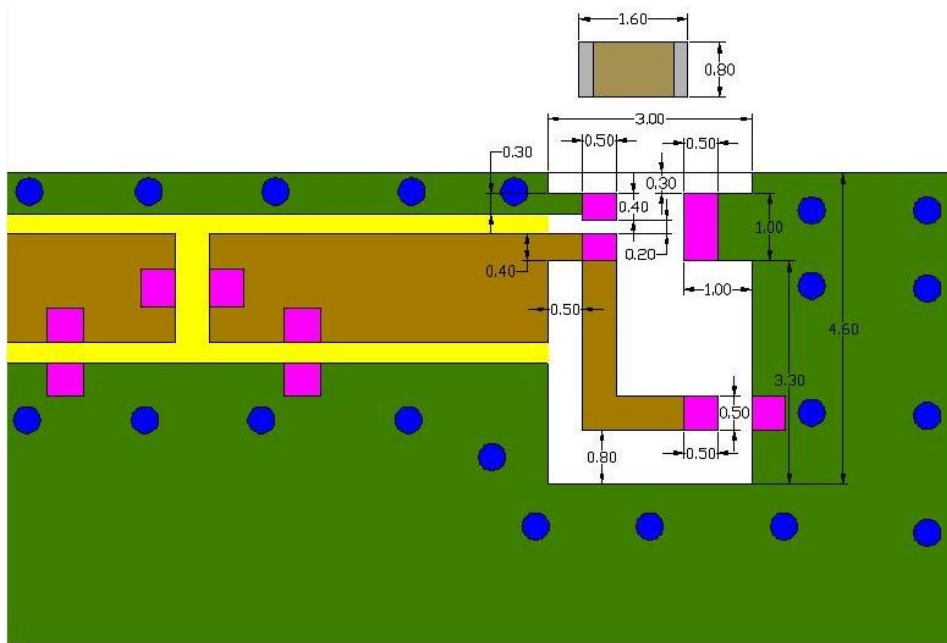
	Efficiency (%)	Peak Gain (dBi)	Efficiency (dB)
2400MHz	65.24%	2.34dBi	-1.85dB
2450MHz	75.51%	2.25 dBi	-1.21dB
2480MHz	64.32%	2.42dBi	-1.91dB

Chamber Coordinate System

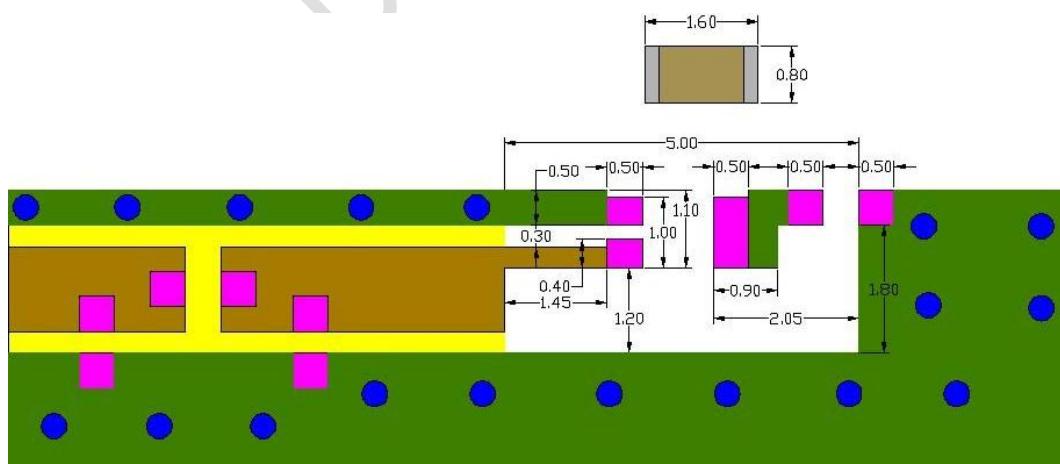


5. Layout Guide:

Solder Land Pattern:

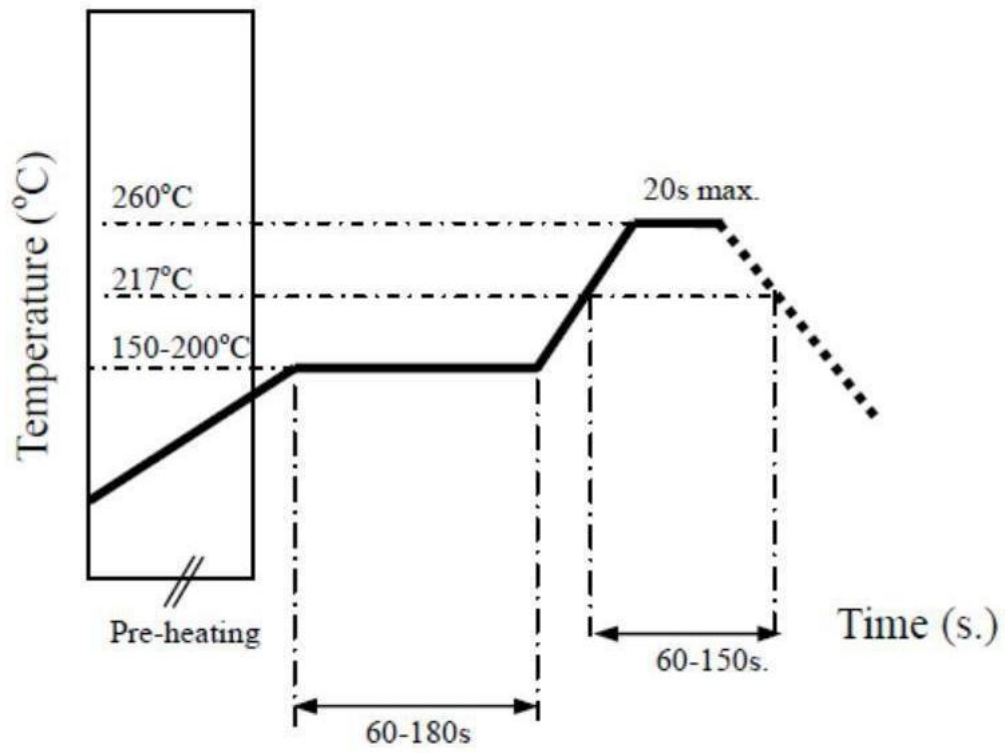


Layout Dimensions in Clearance area (Size=5.0*3.0mm)



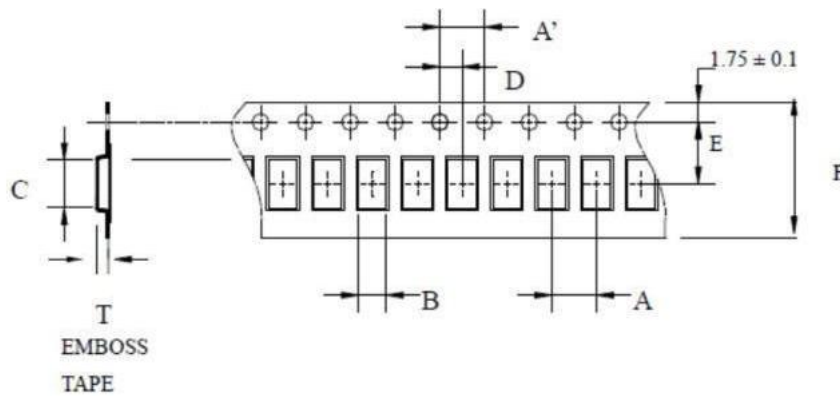
6. Soldering Conditions:

Typical Soldering Profile for Lead-free Process



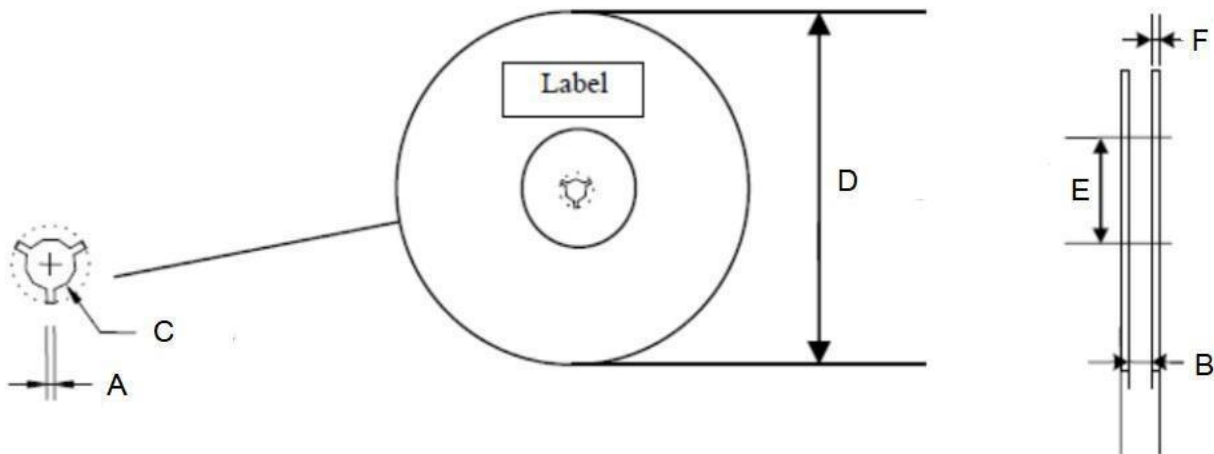
7. Taping Specifications:

Tape Dimensions (Unit: mm) & Quantity



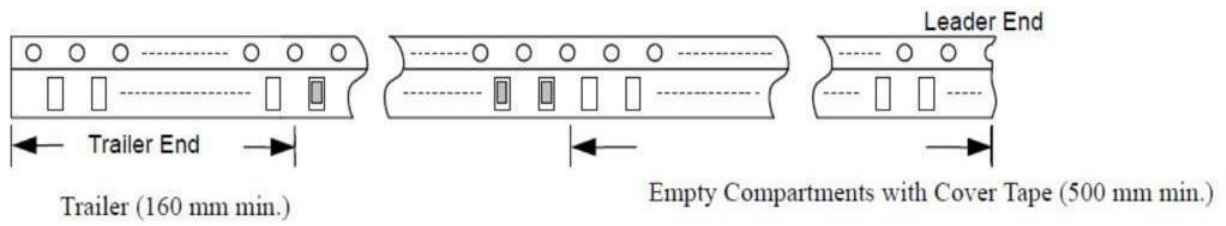
Type	A	A'	B	C	D	E	F	T	Quantity/ Reel	Type Material
DD1608	4.0 ±0.1	4.0 ±0.1	1.95 ±0.1	3.50 ±0.1	2.0 ±0.05	3.5 ±0.1	8.0 ±0.1	0.85 ±0.1	4,000pcs	Plastic (Embossed)

Reel Dimensions (Unit: mm)



Type	A	B	C	D	E	F
DD1608	2.3 ±0.5	17 ±0.5	13.5 ±0.5	178 ±1	75 ±3	1.4 ±0.2

Leader and Trailer Tape



Soldering Conditions:

- (1) Temperature: 5~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment